

CCP-3400

(ST-TYPE)

銅箔積層板-耐漏電絕緣型

COPPER CLAD LAMINATE-ANTI-TRACKING TYPE

長春人造樹脂廠股份有限公司
CHANG CHUN PLASTICS CO., LTD.

CCP-3400

(ST-TYPE)

CCP-3400(ST TYPE)紙基材酚醛樹脂銅箔積層板是針對使用高密度自動插件,晶片零件表面粘著技術等之精密印刷電路板而開發。在高電壓大電流下具有優異的耐電弧發火性,能改善電子產品的安全性。並且可適用於低溫沖孔加工作業。

CCP-3400(ST TYPE), anti-tracking characteristic material, is a newly developed paper based phenolic resin copper clad laminate. It responds to the requirement of high precision printed circuit board made by high density automatic insertion, surface mounting of chip parts,etc. It is excellent in resisting arc sparking due to high voltage and large current, thereby improving safety of electronic devices. It is also suitable for cold punching process.

品名	CCP-3400(ST-TYPE)	
Type		
規格 Grade	ANSI(NEMA)	FR-1
	UL	94V-0
組成 Construction	紙,酚醛樹脂,銅箔 Paper,Phenolic resin, Copper foil.	
特性 Characteristics	<p>*<u>耐漏電絕緣性,高電壓大電流下耐電弧發火性良好。</u> 具有優良的耐漏電絕緣性與耐高壓發火性,適用於高電壓之用途。</p> <p>*<u>High tracking performance and excellent in resisting arc sparking due to high voltage and large current.</u> Suitable for high tension service owing to high tracking performance and excellent high-tension sparking resistance.</p> <p>*<u>低溫沖孔性良好</u> 最適當之沖孔溫度為60~90 。高密度沖孔加工性優良,能改善沖孔後外觀與尺寸精度。</p> <p>*<u>Good punchability at low temperature</u> Optimum punching temperature is 60~90 。 Suitable for high density punching process,permitting improvement of punched appearance and dimensional precision of PCB.</p> <p>*<u>彎曲度,扭曲度小且穩定</u> 印刷電路板加工及零件裝配過程中,彎曲度,扭曲度小且穩定。</p> <p>*<u>Warpage and twist are small and stable</u> During PCB manufacturing and parts mounting process, warpage and twist are small and stable.</p>	

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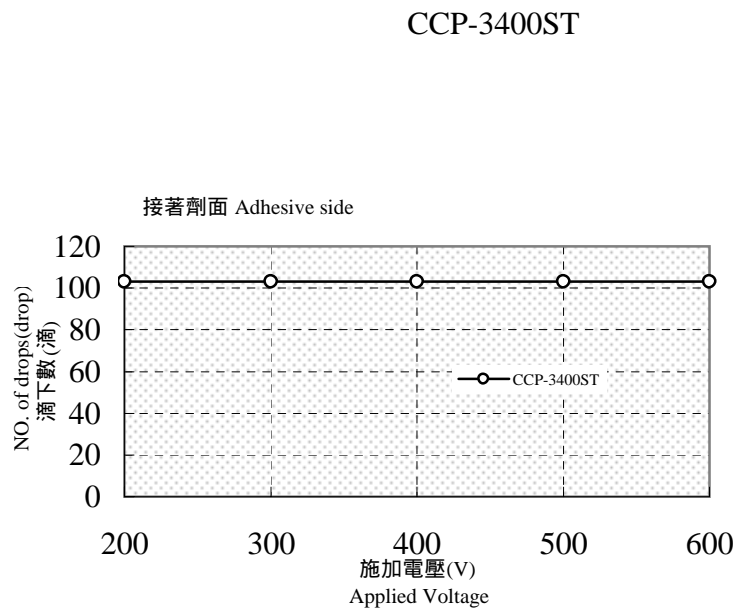
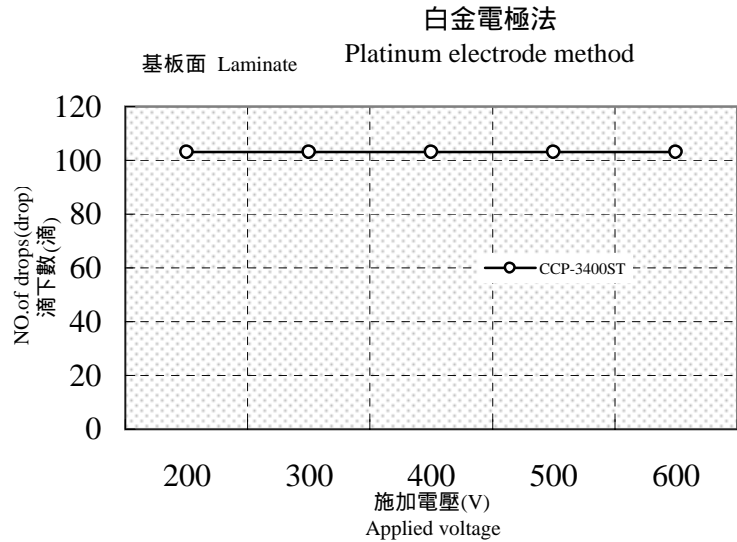
(ST-TYPE)

*IEC法-耐漏電絕緣性

CTI值大於600V,耐漏電絕緣性優良,適合於高電壓之用途。

*IEC METHOD-ANTI-TRACKING PERFORMANCE

Comparative Tracking Index is Over 600V.Suitable for high-tension service because of its excellent anti-tracking performance



試驗方法

Test method

滴 量: 10~30mg/drop

drop quantity

滴下間隔: 1 drop/30sec

dropping pitch

電極間隔: 4mm

electrode distance

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*沖孔性

沖孔加工可使用溫度範圍較大,高密度沖孔加工性良好,孔穴外觀與尺寸精度均可改善

*PUNCHABILITY


Enlarged temperature range for punching, good punchability for high density processing. Dimensional change and the appearance of punched holes are improved.

*沖孔後孔徑收縮

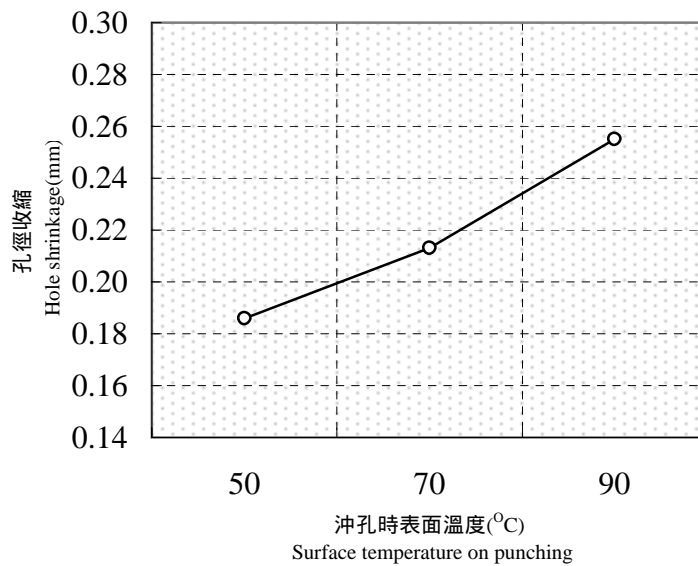
*PUNCHED HOLE SHRINKAGE

最適當沖孔溫度範圍

Optimum temperature range for punching

	沖孔時基板表面溫度				
	Surface temperature range for punching				
	50	60	70	80	90
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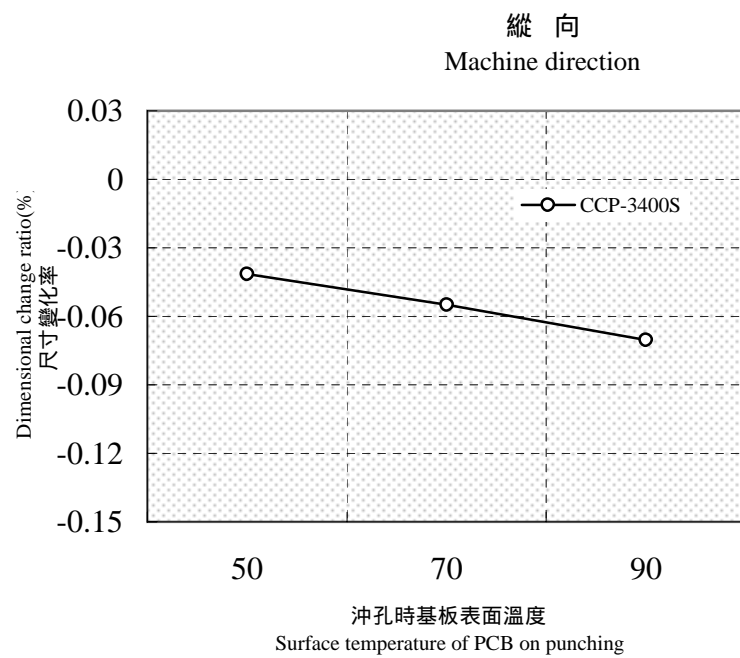
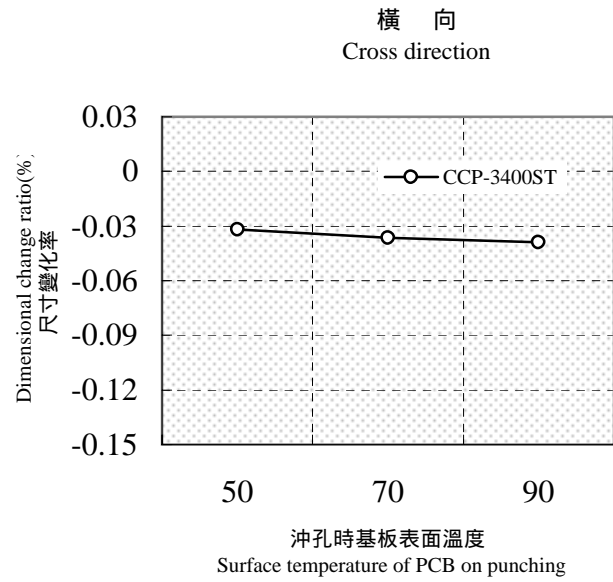


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*沖孔過程之尺寸變化

*DIMENSIONAL
CHANGE OF PCB
PUNCHED



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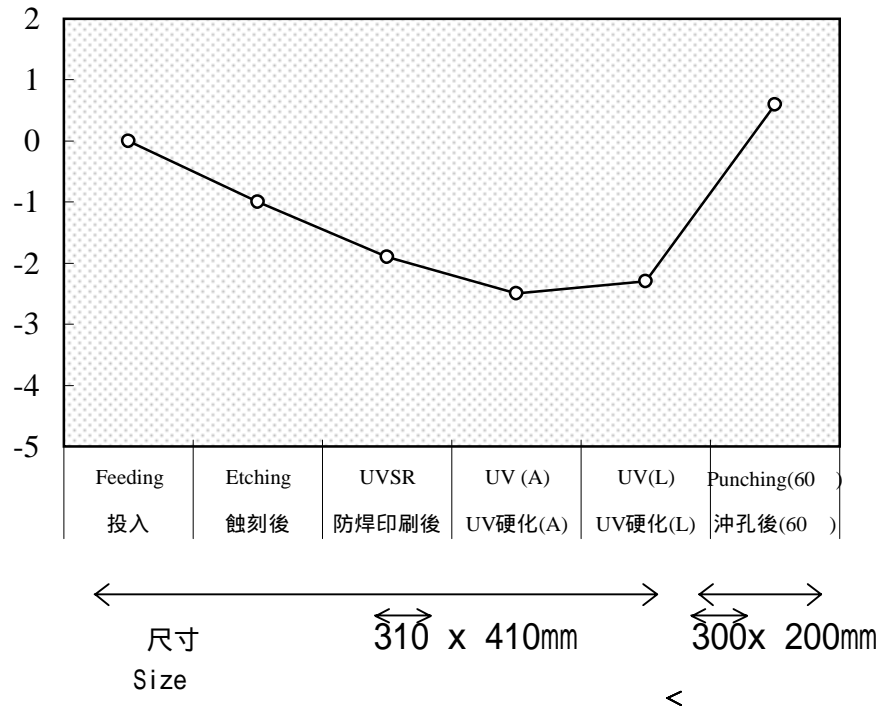
***印刷电路板加工時
彎曲度**

加工過程中,彎曲,扭曲小
且穩定

***WARPAGE OF
PCB IN
PROCESSING**

Warpage and twist are
small and stable during
PCB manufacturing
process

CCP-3400ST



CCP-3400
(ST-TYPE)

*一般性能

*GENERAL

PROPERTIES

試驗項目 Item	單位 Unit	處理條件 Condition	CCP-3400 ST-TYPE
體積阻抗率 Volumn Resistance	-cm	C-96/20/65	4.1×10^{13}
		C-96/20/65 +C-96/40/90	1.7×10^{13}
表面 阻 抗 Surface Resistance	接著劑面 Adhesive Side	C-96/20/65	8.7×10^{11}
		C-96/20/65 +C-96/40/90	2.0×10^{11}
	基板面 Laminate Side	C-96/20/65	1.0×10^{11}
		C-96/20/65 +C-96/40/90	6.4×10^9
絕緣阻抗 Insulation Resistance		C-96/20/65	7.4×10^{12}
		C-96/20/65 +D-2/100	3.3×10^9
介質常數(1MHz) Dielectric Constant		C-96/20/65	4.6
		C-96/20/65 +D-24/23	4.8
散失因子(1MHz) Dissipation Factor		C-96/20/65	0.046
		C-96/20/65 +D-24/23	0.048
吸水率 Water Absorption	%	E-24/50	0.95
		+D-24/23	
焊錫耐熱性 Solder Float(260)	秒 sec	A	35
抗撕強度 Peel Strength	KN/m (kgf/cm)	A	2.1 (2.1)
		S-260 10"	2.1 (2.1)
耐燃性(UL) Flammability	-		UL94 V-0
Flexural Strength 彎折強度	縱向 MD 橫向 CD	KN/mm ² (kgf/mm ²)	A
			130 (13)
耐藥品性 Chemical Resistance	三氯乙烯×3 Trichloroethylene×3		無異常 No apparent change

所表示之特性為實測之參考值(All of the data is for referance)